

PRELIMINARY SPEC

Part Number: WP7083SYD/J

SUPER BRIGHT YELLOW

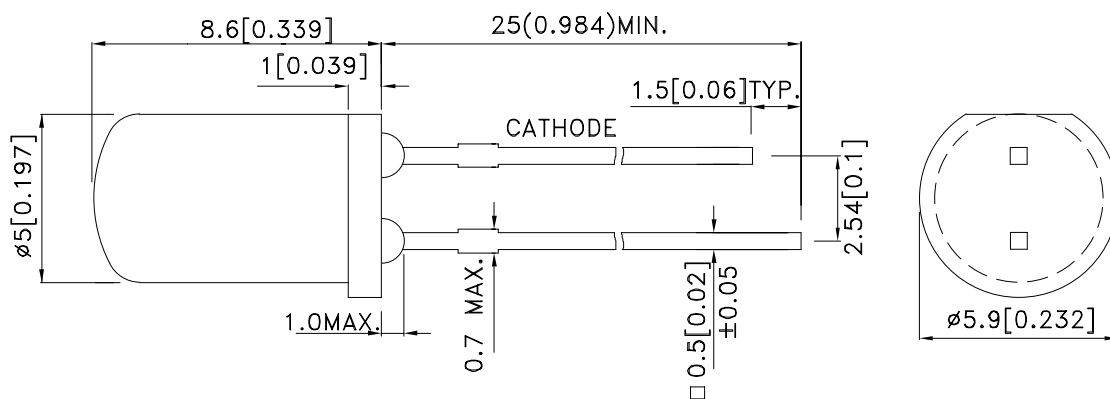
Features

- OUTSTANDING MATERIAL EFFICIENCY.
- RELIABLE AND RUGGED.
- I.C. COMPATIBLE.
- RoHS COMPLIANT.

Description

The Super Bright device is based on light emitting diode chip made from AlInGaP.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP7083SYD/J	SUPER BRIGHT YELLOW (AlInGaP)	YELLOW DIFFUSED	280	800	60°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Super Bright Yellow	590		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	Super Bright Yellow	589		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Super Bright Yellow	20		nm	I _F =20mA
C	Capacitance	Super Bright Yellow	45		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Super Bright Yellow	2.3	2.8	V	I _F =20mA
I _R	Reverse Current	Super Bright Yellow		10	uA	V _R = 5V

Notes:

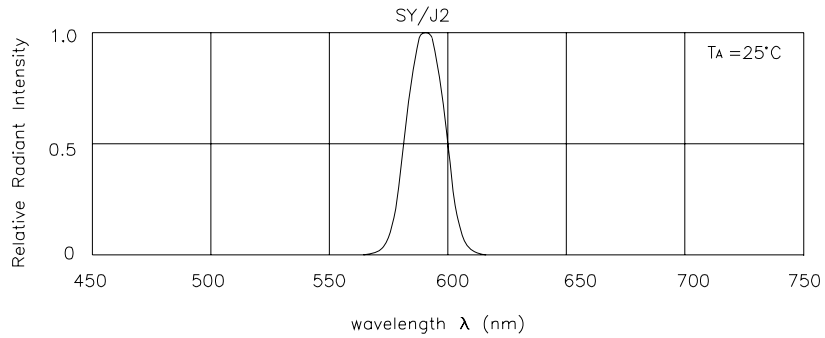
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Yellow	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

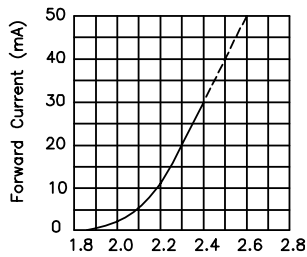
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.

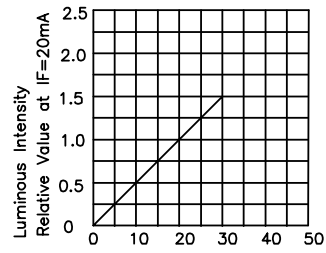


RELATIVE INTENSITY Vs. WAVELENGTH

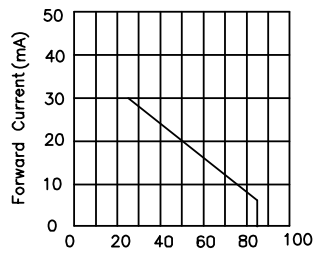
Super Bright Yellow WP7083SYD/J



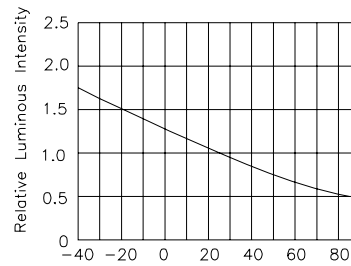
Forward Voltage(V)
FORWARD CURRENT Vs.
FORWARD VOLTAGE



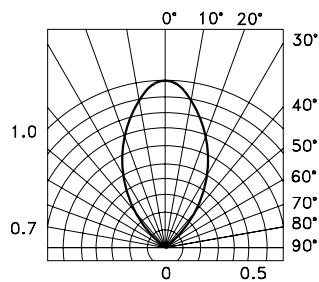
If—Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



Ambient Temperature T_A (°C)
FORWARD CURRENT
DERATING CURVE



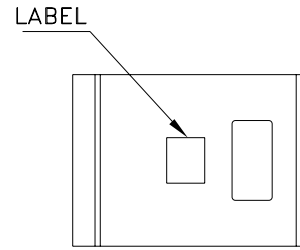
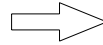
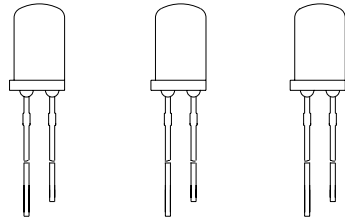
Ambient Temperature T_A (°C)
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

PACKING & LABEL SPECIFICATIONS

WP7083SYD/J

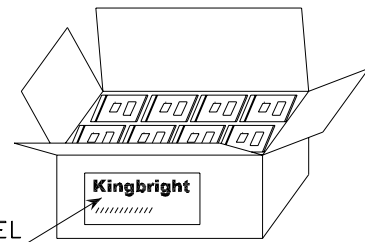
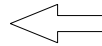


500PCS / BAG




20K / 9# BOX

OUTSIDE LABEL



10K / 5# BOX

OUTSIDE LABEL

Kingbright				
Q.C.	<table border="1"> <tr> <td style="text-align: center;">QC</td> </tr> <tr> <td style="text-align: center;">XX XX XX</td> </tr> <tr> <td style="text-align: center;">PASSED</td> </tr> </table>	QC	XX XX XX	PASSED
QC				
XX XX XX				
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TYPE NO : WP7083xxx				
QUANTITY : 500 pcs				
S/N : XX	CODE: XX			
LOT NO :  xxxxxxxxxxxx				
RoHS Compliant				

LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

(Fig. 1)



Fig.1

“○” Correct mounting method “X” Incorrect mounting method

Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit.

(Fig. 2)



Fig. 2

3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

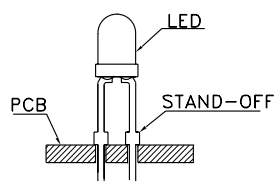


Fig. 3



Fig. 4

LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



Fig. 5



Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after Soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
5. Do not bend the leads more than twice. (Fig. 8)



Fig. 7



Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



Fig. 9

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- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

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Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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